

IN THE CLAIMS:

Please CANCEL claims 1, 2, 4-6, 13 and 15 without prejudice to or disclaimer of the recited subject matter.

For the Examiner's convenience, all claims currently presented are reproduced below.

1-6. (Canceled)

7. (Previously Presented) A measuring apparatus for measuring a position of a surface of an object while the object is scanned in a scanning direction in an X-Y plane, said apparatus comprising:

a detecting unit configured to detect the position of the surface of the object in a Z direction perpendicular to the X-Y plane;

a stage configured to scan the object relative to said detecting unit in the scanning direction; and

a controller configured to cause said stage to scan the object relative to said detecting unit in two scanning directions, in the X-Y plane, opposite to each other, to detect, using said detecting unit, with respect to each of the two scanning directions, a position of the surface in the Z direction for the same detection point on the surface, to calculate a correction value for correcting a position of the surface to be detected by said detecting unit while the object is scanned relative to said detecting unit in one of the two scanning directions, based on the positions of the surface detected for the same detection point with respect to the two scanning directions, and to correct the position of the surface detected by said detecting unit while the

object is scanned relative to said detecting unit in the one of the two scanning directions, with the calculated correction value.

8. (Previously Presented) A measuring apparatus according to claim 7, wherein the object is a semiconductor wafer.

9. (Canceled)

10. (Previously Presented) A measuring apparatus according to claim 7, wherein said controller is configured to cause said detecting unit to detect the position of the surface with respect to each of a plurality of sample shot regions on the surface.

11. (Previously Presented) A measuring apparatus according to claim 7, wherein said controller is configured to weighted-average the positions of the surface detected for the same point with respect to the two scanning directions, and to calculate the correction value based on the weighted average.

12. (Previously Presented) A measuring apparatus according to claim 10, wherein said controller is configured to choose data of the position of the surface to be used for calculation of the correction value, based on a difference between the positions of the surface detected for the same position with respect to the two scanning directions.

13-15. (Canceled)